

What is claimed is:

[Claim 1] 1. A bonding pad for disposing on a chip, comprising:

 a body having a first surface and a corresponding second surface, wherein the body is disposed on the chip, and the second surface of the body is in contact with the chip; and

 at least one first protruding portion disposed on the first surface at the corner regions of the body.

[Claim 2] 2. The bonding pad of claim 1, further comprising a second protruding portion disposed on the first surface in the central region of the body.

[Claim 3] 3. The bonding pad of claim 2, wherein the second protruding portion is connected to the first protruding portion.

[Claim 4] 4. The bonding pad of claim 2, wherein the shape of the second protruding portion when viewed from the top against the first surface is selected from the group consisting of a cross-line shape, a circular shape, a circular ring shape, an ellipse shape, an ellipse ring shape, a polygonal shape, a polygonal ring shape, a linear shape, a geometrical shape and combinations thereof .

[Claim 5] 5. The bonding pad of claim 3, wherein the shape of the second protruding portion when viewed from the top against the first surface is selected from the group consisting of a cross-line shape, a circular shape, a circular ring shape, an ellipse shape, an ellipse ring shape, a polygonal shape, a polygonal ring shape, a linear shape, a geometrical shape and combinations thereof.

[Claim 6] 6. The bonding pad of claim 2, wherein the body, the first protruding portion and the second protruding portion are formed together as single unit.

[Claim 7] 7. The bonding pad of claim 1, wherein the body and the first protruding portion are formed together as a single unit.

[Claim 8] 8. The bonding pad of claim 1, wherein the material constituting the bonding pad comprises aluminum.

[Claim 9] 9. The bonding pad of claim 1, wherein the body has a four-sided geometric shape.

[Claim 10] 10. A chip structure, comprising:

a chip having an active surface;

at least one bonding pad disposed on the active surface of the chip, the bonding pad including:

a body having a first surface and a corresponding second surface, wherein the body is disposed on the chip, and the second surface of the body is in contact with the chip; and

at least one first protruding portion disposed on the first surface at the corner regions of the body.

[Claim 11] 11. The chip structure of claim 10, wherein the bonding pad further comprises a second protruding portion disposed on the first surface in the central region of the body.

[Claim 12] 12. The chip structure of claim 11, wherein the second protruding portion is connected to the first protruding portion.

[Claim 13] 13. The chip structure of claim 11, wherein the shape of the second protruding portion when viewed from the top against the first surface is selected from the group consisting of a cross-line shape, a circular shape, a circular ring shape, an ellipse shape, an ellipse ring shape, a polygonal shape, a polygonal ring shape, a linear shape, a geometrical shape and combinations thereof.

[Claim 14] 14. The chip structure of claim 12, wherein the shape of the second protruding portion when viewed from the top against the first surface is selected from the group consisting of a cross-line shape, a circular shape, a circular ring shape, an ellipse shape, an ellipse ring shape, a polygonal shape, a polygonal ring shape, a linear shape, a geometrical shape and combinations thereof.

[Claim 15] 15. The chip structure of claims 11, wherein the bonding pad is a single unit.

[Claim 16] 16. The chip structure of claims 10, wherein the bonding pad is a single unit.

[Claim 17] 17. The chip structure of claim 10, wherein the material constituting the bonding pad comprises aluminum.

[Claim 18] 18. The chip structure of claim 10, wherein the body has a four-sided geometric shape.

[Claim 19] 19. The chip structure of claim 10, further comprising a passivation layer disposed on the active surface of the chip that also covers the peripheral region of the bonding pad but leaves the central region of the bonding pad exposed.

[Claim 20] 20. The chip structure of claim 10, further comprising at least a bump disposed on and electrically connected with the bonding pad.

[Claim 21] 21. A pad for disposing on a chip, comprising:

a body; and

at least one first protruding portion disposed on corner regions of the body.

[Claim 22] 22. The pad of claim 21, further comprising a second protruding portion disposed on central region of the body.

[Claim 23] 23. A display apparatus comprising a device which includes the pad of claim 21.

[Claim 24] 24. The display apparatus of claim 23, wherein the pad further comprises a second protruding portion disposed on central region of the body.

[Claim 25] 25. The display apparatus of claim 24, wherein the second protruding portion is connected to the first protruding portion.

[Claim 26] 26. A device comprising the pad of claim 21.

[Claim 27] 27. The device of claim 26, wherein the pad further comprises a second protruding portion disposed on central region of the body.

[Claim 28] 28. The device of claim 27, wherein the second protruding portion is connected to the first protruding portion.